

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.26	100.0	5.1
<b>Subtotal</b>				<b>0.26</b>	<b>100</b>	<b>5.1</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03	0.04	0.53
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	1.32
	Copper alloy	Copper (Cu)	7440-50-8	68.53	99.86	1321.85
<b>Subtotal</b>				<b>68.63</b>	<b>100</b>	<b>1323.7</b>
Mould Compound		Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.38	1.3	7.31
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.04	7.0	39.38
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.08	14.0	78.75
	Filler	Silica fused	60676-86-0	1.75	6.0	33.75
	Carbon Black	Carbon black	1333-86-4	0.12	0.4	2.25
	Filler	Misc. Silica compounds (generic)	14808-60-7	20.41	70.0	393.75
		Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.38	1.3	7.31
<b>Subtotal</b>				<b>29.16</b>	<b>100</b>	<b>562.5</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.4	100.0	27
<b>Subtotal</b>				<b>1.4</b>	<b>100</b>	<b>27</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.27
	Pure metal	Aluminium (Al)	7429-90-5	0.12	100.0	2.4
<b>Subtotal</b>				<b>0.13</b>	<b>200</b>	<b>2.67</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	5.0	0.4
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.2
	Lead alloy	Lead (Pb)	7439-92-1	0.38	92.5	7.4
<b>Subtotal</b>				<b>0.41</b>	<b>100</b>	<b>8</b>
<b>Total</b>				<b>99.99</b>	<b>100</b>	<b>1928.97</b>

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